

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re the Application of

Masayuki Yasuda

Docket No.: TIJ-24816

Serial No.: TBD

Art Unit: TBD

Filed: 2/5/98

Examiner: TBD

Title: Manufacturing Method of Semiconductor IC Device

PRELIMINARY AMENDMENT

2/5/98

Assistant Commissioner for Patents
Box New Patent Applications
Washington, D. C. 20231

"EXPRESS MAIL" mailing label number
TB309670273US, Date of Deposit: 2/5/98. I
hereby certify that the accompanying
Application is being deposited with the United
States Postal Service "Express Mail Post
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on the date indicated above and is addressed
to the Assistant Commissioner for Patents,
Washington, DC 20231.


Patricia J. Jones

Sir:

Prior to the examination of the above-identified application,
Applicants respectfully submit the following amendments and remarks.

IN THE CLAIMS:

Please amend Claims 1-5 as follows:

5/10/98
A1
1. (Amended) A manufacturing method of a semiconductor IC
device, [characterized by the fact that it consists of] comprising
the following steps [of operation]:

forming [a step in which] an insulating film [is formed] on a
semiconductor substrate or SOI substrate;

forming [a step in which] a first mask film [is formed] on the
[aforementioned] insulating film;